

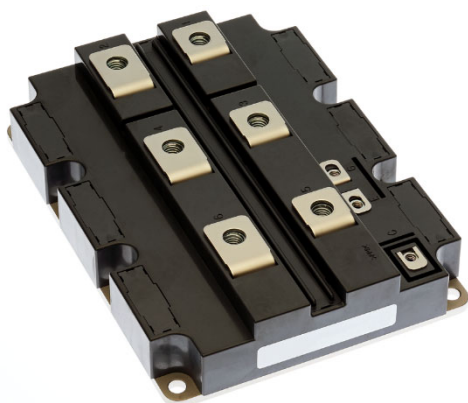
< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM1800HC-66X

HIGH POWER SWITCHING USE
INSULATED TYPE

5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

CM1800HC-66X



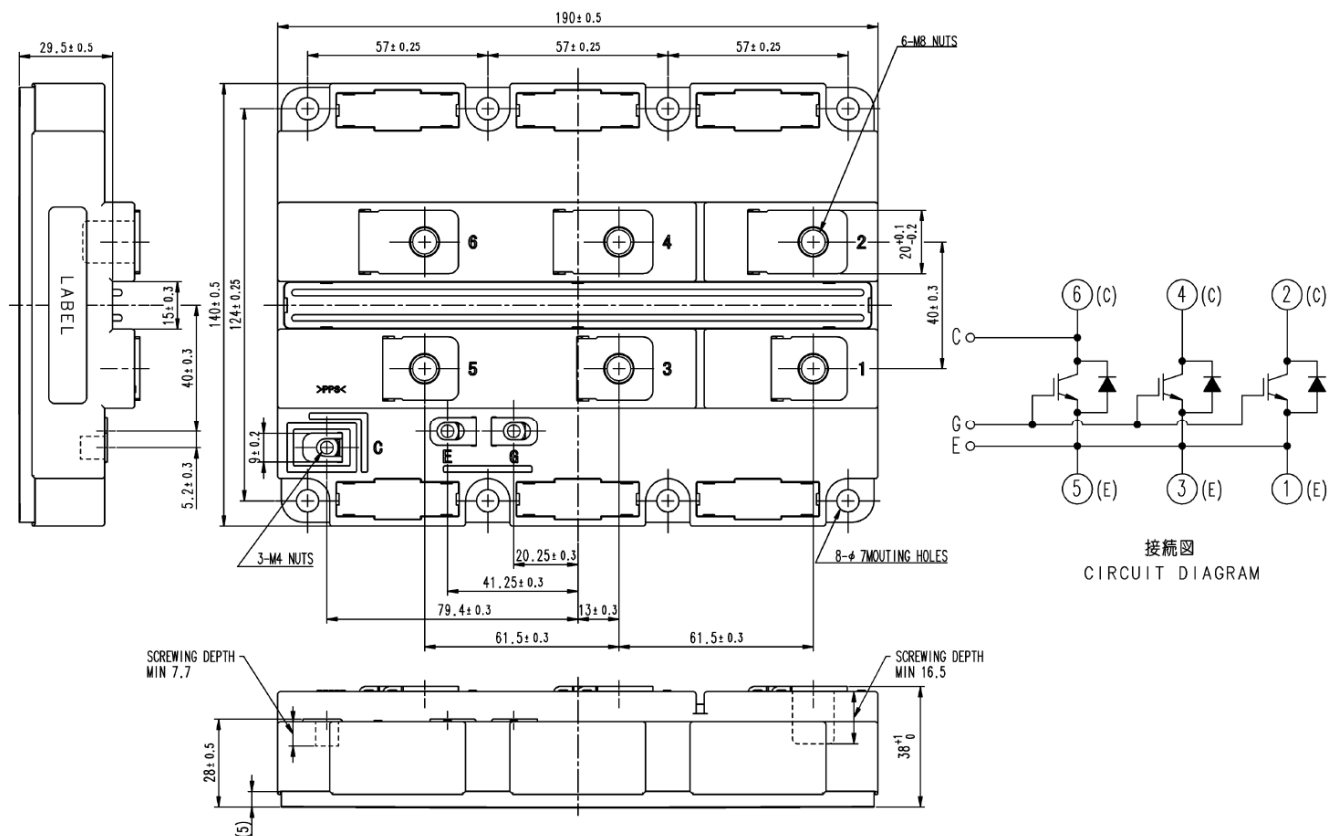
- I_C 1800A
- V_{CES} 3300V
- 1-element in a Pack
- Insulated Type
- CSTBT™(III)
- RFC Diode
- AlSiC Baseplate
- UL recognized under UL1557

APPLICATION

Traction drives, High Reliability Converters / Inverters, DC choppers

OUTLINE DRAWING & CIRCUIT DIAGRAM

Dimensions in mm



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MAXIMUM RATINGS

Symbol	Item	Conditions	Ratings	Unit
V_{CES}	Collector-emitter voltage	$V_{GE} = 0V, T_J = -40...+150^{\circ}C$	3300	V
		$V_{GE} = 0V, T_J = -50^{\circ}C$	3200	
V_{GES}	Gate-emitter voltage	$V_{CE} = 0V, T_J = 25^{\circ}C$	± 20	V
I_C	Collector current	DC, $T_c = 105^{\circ}C$	1800	A
I_{CRM}		Pulse (Note 1)	3600	A
I_E	Emitter current (Note 2)	DC, $T_c = 90^{\circ}C$	1800	A
I_{ERM}		Pulse (Note 1)	3600	A
P_{tot}	Maximum power dissipation (Note 3)	$T_c = 25^{\circ}C$, IGBT part	17800	W
V_{iso}	Isolation voltage	RMS, sinusoidal, $f = 60Hz, t = 1min.$	6000	V
V_e	Partial discharge extinction voltage	RMS, sinusoidal, $f = 60Hz, Q_{PD} \leq 10pC$	2600	V
T_J	Junction temperature		$-50 \sim +150$	$^{\circ}C$
T_{Jop}	Operating junction temperature		$-50 \sim +150$	$^{\circ}C$
T_{stg}	Storage temperature		$-55 \sim +150$	$^{\circ}C$
t_{psc}	Short circuit pulse width	$V_{CC} = 2500V, V_{CE} \leq V_{CES}, V_{GE} = 15V, T_J = 150^{\circ}C$	10	μs

ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions		Limits			Unit
				Min	Typ	Max	
I _{CES}	Collector cutoff current	V _{CE} = V _{CES} , V _{GE} = 0V	T _J = 25°C	—	—	6.0	mA
			T _J = 125°C	—	6.0	—	
			T _J = 150°C	—	36.0	—	
V _{GE(th)}	Gate-emitter threshold voltage	V _{CE} = 10V, I _C = 180mA, T _J = 25°C		6.5	7.0	7.5	V
I _{GES}	Gate leakage current	V _{GE} = V _{GES} , V _{CE} = 0V, T _J = 25°C		-0.5	—	0.5	μA
C _{ies}	Input capacitance	V _{CE} = 10V, V _{GE} = 0V, f = 100kHz T _J = 25°C		—	208	—	nF
C _{oes}	Output capacitance			—	14.0	—	
C _{res}	Reverse transfer capacitance			—	1.9	—	
Q _G	Total gate charge	V _{CC} = 1800V, I _C = 1800A, V _{GE} = ±15V		—	13.5	—	μC
V _{CEsat}	Collector-emitter saturation voltage	I _C = 1800A (Note 4) V _{GE} = 15V	T _J = 25°C	—	2.00	—	V
			T _J = 125°C	—	2.50	—	
			T _J = 150°C	—	2.60	3.10	
t _{d(on)}	Turn-on delay time	V _{CC} = 1800V I _C = 1800A V _{GE} = ±15V R _{G(on)} = 1.5Ω L _S = 100nH Inductive load	T _J = 150°C	—	—	0.90	μs
t _r	Turn-on rise time		T _J = 150°C	—	—	0.50	μs
E _{on(10%)}	Turn-on switching energy (Note 7)		T _J = 25°C	—	2.95	—	J
			T _J = 125°C	—	3.25	—	
			T _J = 150°C	—	3.40	—	
E _{on}	Turn-on switching energy (Note 5)		T _J = 25°C	—	3.00	—	J
			T _J = 125°C	—	3.40	—	
			T _J = 150°C	—	3.55	—	
t _{d(off)}	Turn-off delay time	T _J = 25°C	—	2.90	—	μs	
		T _J = 125°C	—	3.20	—		
		T _J = 150°C	—	3.20	4.25		
t _f	Turn-off fall time	V _{CC} = 1800V I _C = 1800A V _{GE} = ±15V R _{G(off)} = 12Ω L _S = 100nH Inductive load	T _J = 25°C	—	0.40	—	μs
		T _J = 125°C	—	0.45	—		
		T _J = 150°C	—	0.50	1.00		
E _{off(10%)}	Turn-off switching energy (Note 7)	T _J = 25°C	—	2.30	—	J	
		T _J = 125°C	—	3.05	—		
		T _J = 150°C	—	3.10	—		
E _{off}	Turn-off switching energy (Note 5)	T _J = 25°C	—	2.45	—	J	
		T _J = 125°C	—	3.10	—		
		T _J = 150°C	—	3.35	—		

CM1800HC-66X

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ELECTRICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
V_{EC}	Emitter-collector voltage (Note 2)	$I_E = 1800A$ (Note 4) $V_{GE} = 0V$	$T_J = 25^\circ C$	—	2.20	V
			$T_J = 125^\circ C$	—	2.40	
			$T_J = 150^\circ C$	—	2.50	
t_{rr}	Reverse recovery time (Note 2)		$T_J = 25^\circ C$	—	0.95	μs
			$T_J = 125^\circ C$	—	1.10	
			$T_J = 150^\circ C$	—	1.15	
I_{rr}	Reverse recovery current (Note 2)		$T_J = 25^\circ C$	—	—	A
			$T_J = 125^\circ C$	—	2350	
			$T_J = 150^\circ C$	—	2500	
$Q_{rr(10\%)}$	Reverse recovery charge (Note 2,6)	$V_{CC} = 1800V$ $I_E = 1800A$ $V_{GE} = \pm 15V$ $R_{G(on)} = 1.5\Omega$ $L_S = 100nH$ Inductive load	$T_J = 25^\circ C$	—	1600	μC
			$T_J = 125^\circ C$	—	2400	
			$T_J = 150^\circ C$	—	2500	
Q_{rr}	Reverse recovery charge (Note 2,5)		$T_J = 25^\circ C$	—	1800	μC
			$T_J = 125^\circ C$	—	2600	
			$T_J = 150^\circ C$	—	2700	
$E_{rec(10\%)}$	Reverse recovery energy (Note 2,7)		$T_J = 25^\circ C$	—	1.70	J
			$T_J = 125^\circ C$	—	2.45	
			$T_J = 150^\circ C$	—	2.80	
E_{rec}	Reverse recovery energy (Note 2,5)		$T_J = 25^\circ C$	—	1.85	J
			$T_J = 125^\circ C$	—	2.60	
			$T_J = 150^\circ C$	—	2.95	

THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
$R_{th(j-c)Q}$	Thermal resistance	Junction to Case, IGBT part	—	—	7.0	K/kW
$R_{th(j-c)D}$		Junction to Case, FWDi part	—	—	11.0	K/kW
$R_{th(c-s)}$	Contact thermal resistance	Case to heat sink $\lambda_{grease} = 1W/m^2 \cdot K$, $D_{(c-s)} = 80\mu m$	—	5.0	—	K/kW

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
M_t	Mounting torque	M8 : Main terminals screw	7.0	—	19.0	N·m
M_s		M6 : Mounting screw	3.0	—	6.0	N·m
M_t		M4 : Auxiliary terminals screw (Note 8)	1.0	—	3.0	N·m
M	Mass		—	1.2	—	kg
CTI	Comparative tracking index		600	—	—	—
d_a	Clearance		19.5	—	—	mm
d_s	Creepage distance		32.0	—	—	mm
$L_{P_{CE}}$	Parasitic stray inductance		—	8.0	—	nH
$R_{CC'+EE'}$	Internal lead resistance	$T_C = 25^\circ C$	—	0.09	—	mΩ

Note1. Pulse width and repetition rate should be such that junction temperature (T_J) does not exceed T_{Jopmax} rating.

Note2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

Note3. Junction temperature (T_J) should not exceed T_{Jmax} rating ($150^\circ C$).

Note4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

Note5. Definition of all items is according to IEC 60747, unless otherwise specified.

Note6. The integration range of reverse recovery charge is from $I_E = 0A$ to $10\%I_E$.Note7. The integration range of switching energies is from $10\%V_{CE}$ to $10\%I_C(10\%I_E)$.

Note8. The maximum specified value is under the condition of using PCB mounted on the power module. In case no PCB is used this maximum torque for M4 screw is 2.0 Nm.

CM1800HC-66X

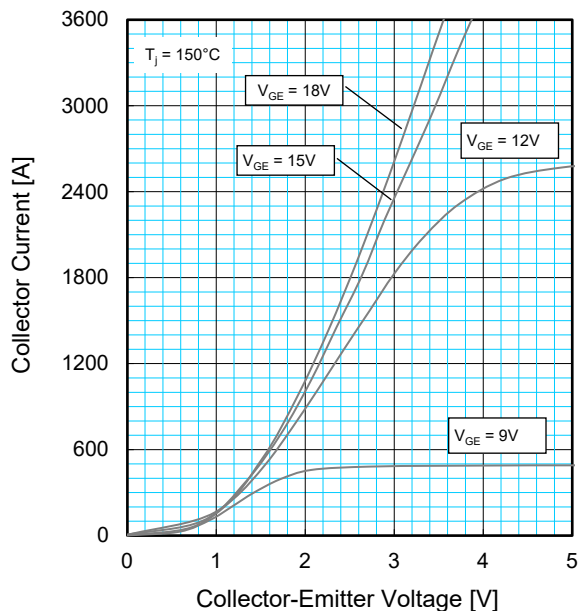
HIGH POWER SWITCHING USE

INSULATED TYPE

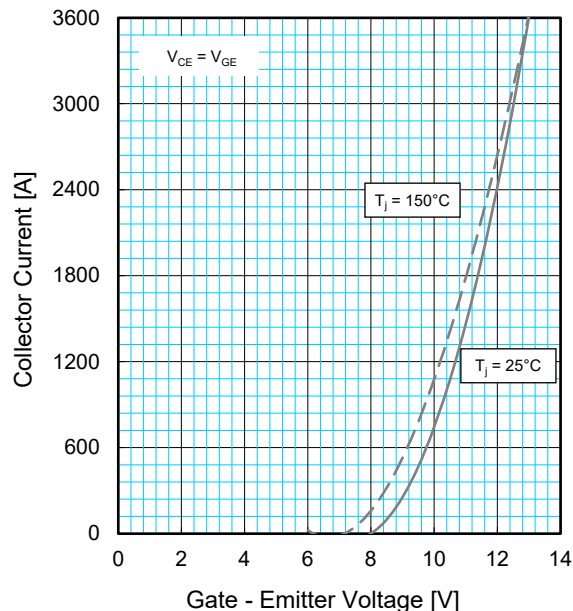
5th-Version HVIGBT (High Voltage Insulated Gate Bipolar Transistor) Modules

PERFORMANCE CURVES

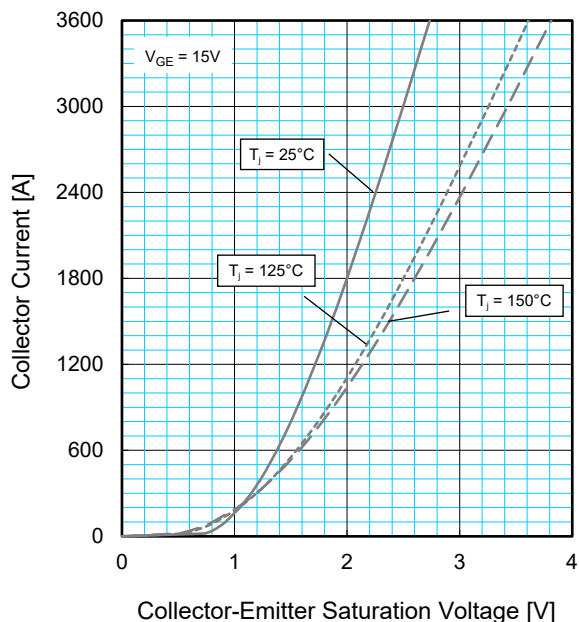
OUTPUT CHARACTERISTICS
(TYPICAL)



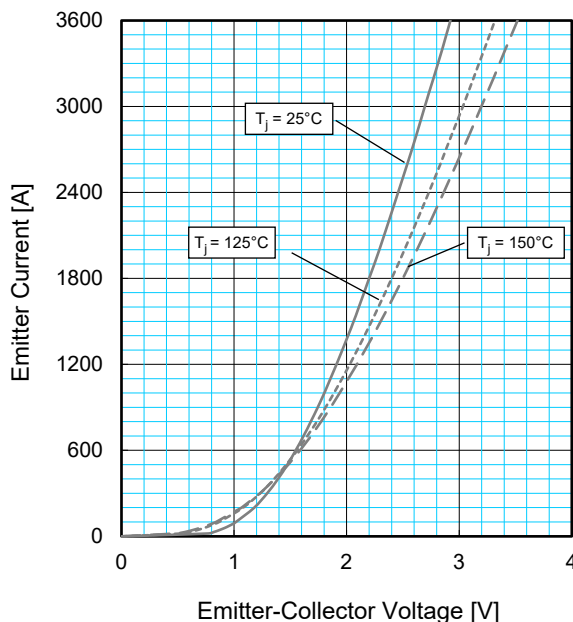
TRANSFER CHARACTERISTICS
(TYPICAL)



COLLECTOR-EMITTER SATURATION VOLTAGE
CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE FORWARD
CHARACTERISTICS (TYPICAL)



CM1800HC-66X

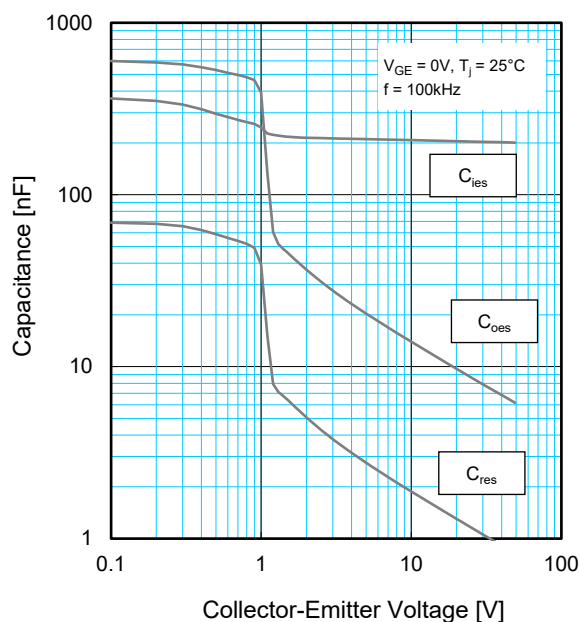
HIGH POWER SWITCHING USE

INSULATED TYPE

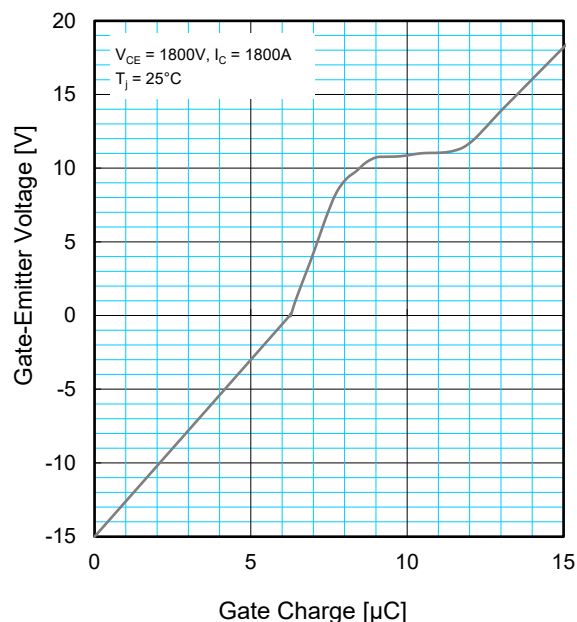
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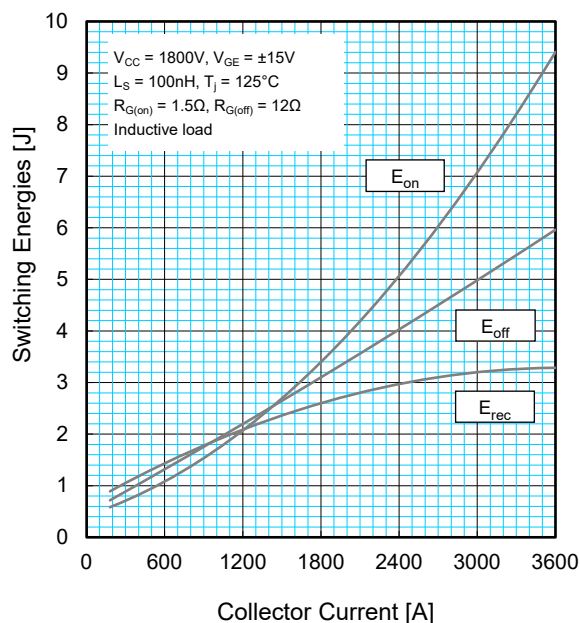
CAPACITANCE CHARACTERISTICS
(TYPICAL)



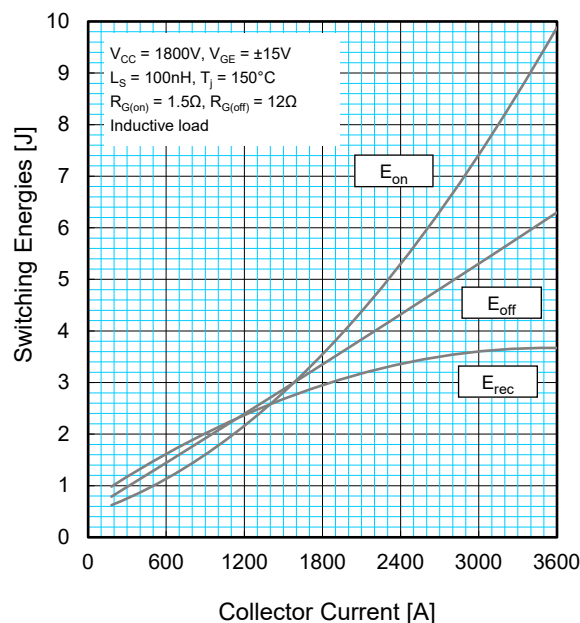
GATE CHARGE CHARACTERISTICS
(TYPICAL)



HALF-BRIDGE SWITCHING ENERGY
CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING ENERGY
CHARACTERISTICS (TYPICAL)



CM1800HC-66X

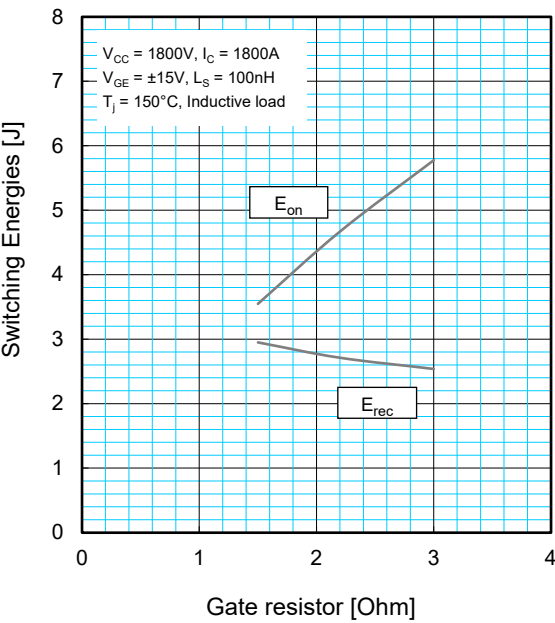
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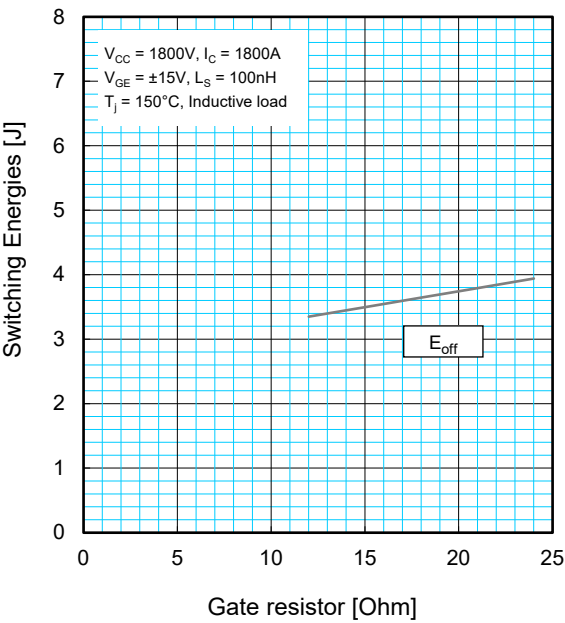
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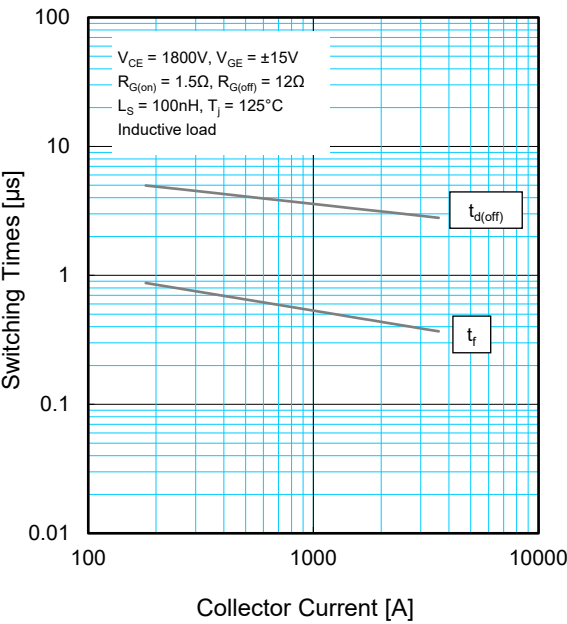
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



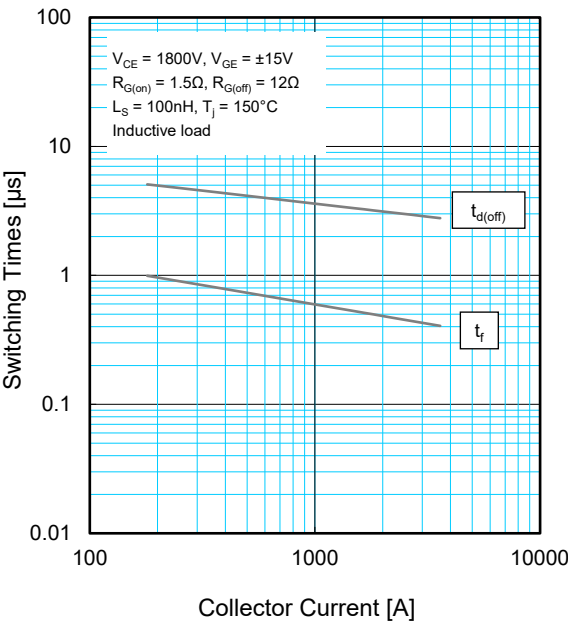
HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



CM1800HC-66X

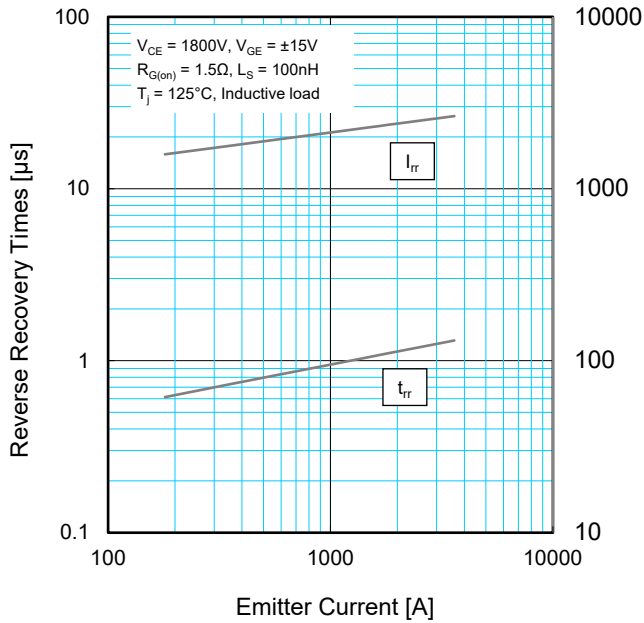
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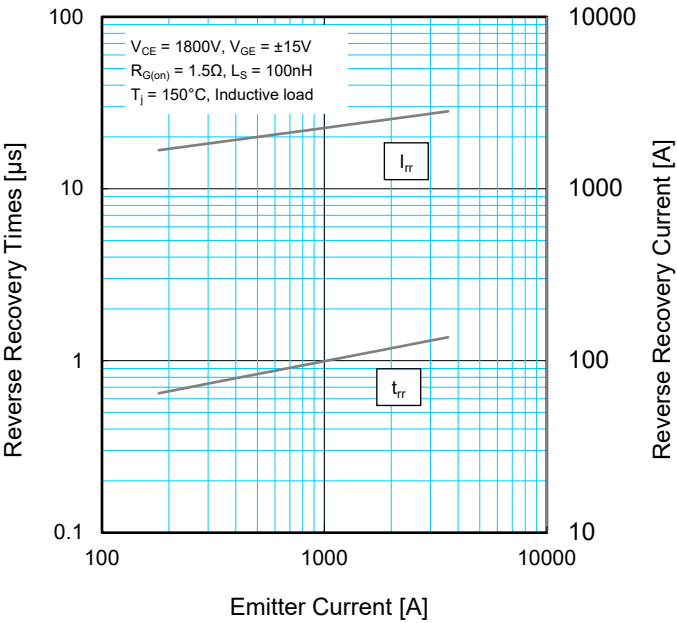
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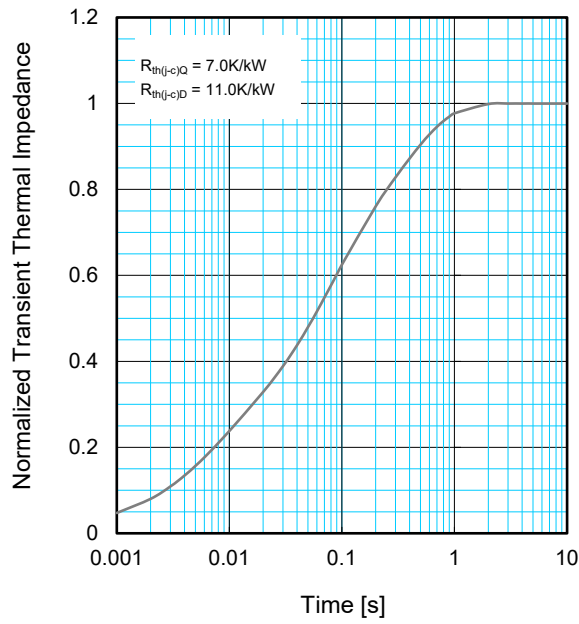
FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i \left\{ 1 - \exp\left(-\frac{t}{\tau_i}\right) \right\}$$

	1	2	3	4
$R_i / R_{th(j-c)} :$	0.0096	0.1893	0.4044	0.3967
$\tau_i [\text{sec}] :$	0.0001	0.0058	0.0602	0.3512

CM1800HC-66X

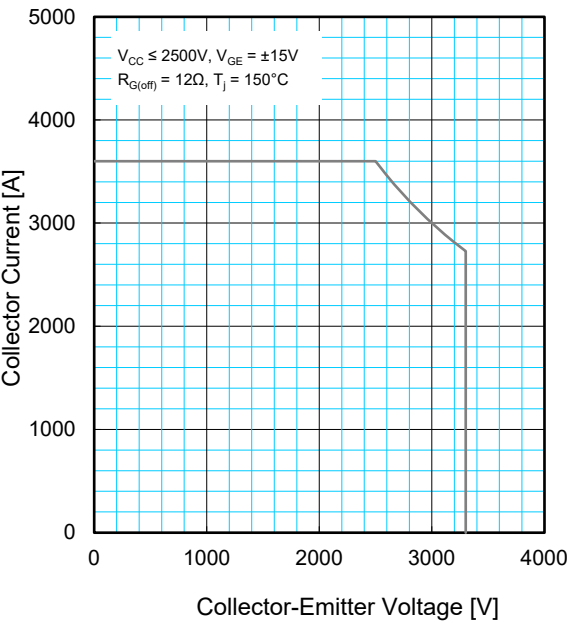
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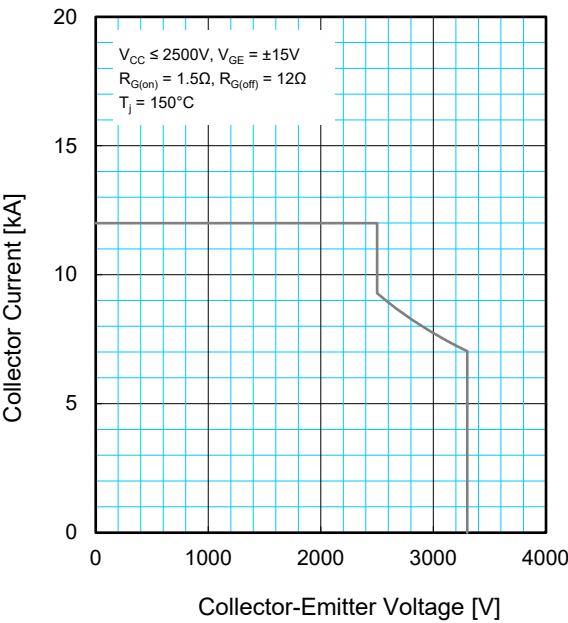
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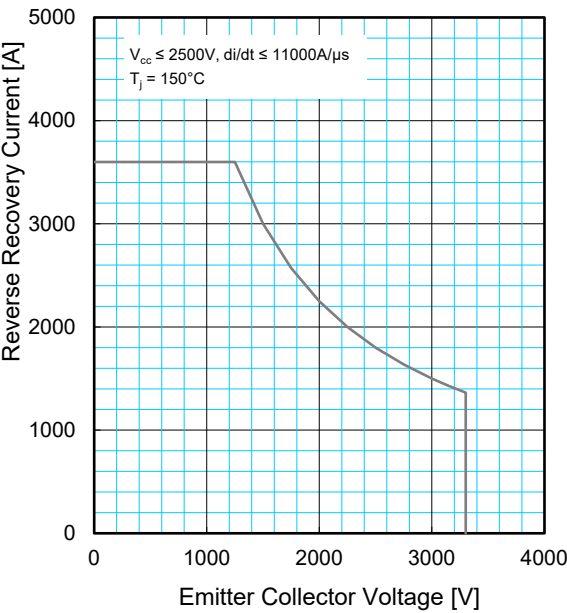
REVERSE BIAS SAFE OPERATING AREA (RBSOA)



SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)



FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)



CM1800HC-66X

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